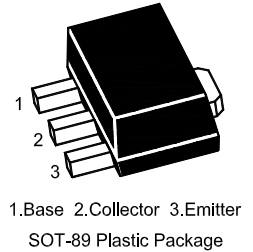


PNP Silicon Epitaxial Planar Transistor

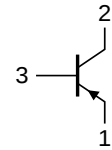
FEATURES

- SOT89 package
- Low collector-emitter saturation voltage V_{CEsat}
- High collector current capability: I_C and I_{CM}
- Higher efficiency leading to less heat generation
- Reduced printed-circuit board requirements.



APPLICATIONS

- Power management
 - DC/DC converters
 - Supply line switching
 - Battery charger
 - LCD backlighting.



MARKING: 1S

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	–30	V
V_{CEO}	collector-emitter voltage	open base	–	–30	V
V_{EBO}	emitter-base voltage	open collector	–	–6	V
I_C	collector current (DC)	note 4	–	–3	A
I_{CM}	peak collector current	limited by $T_{j(max)}$	–	–5	A
I_B	base current (DC)		–	–0.5	A
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ }^{\circ}\text{C}$			
		note 1	–	550	mW
		note 2	–	1	W
		note 3	–	1.4	W
		note 4	–	1.6	W
T_{stg}	storage temperature		–65	+150	$^{\circ}\text{C}$
T_j	junction temperature		–	150	$^{\circ}\text{C}$
T_{amb}	ambient temperature		–65	+150	$^{\circ}\text{C}$

Notes

1. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; standard footprint.
2. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; mounting pad for collector 1 cm².
3. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; mounting pad for collector 6 cm².
4. Device mounted on a ceramic printed-circuit board 7 cm², single-sided copper, tin-plated.

CHARACTERISTICS

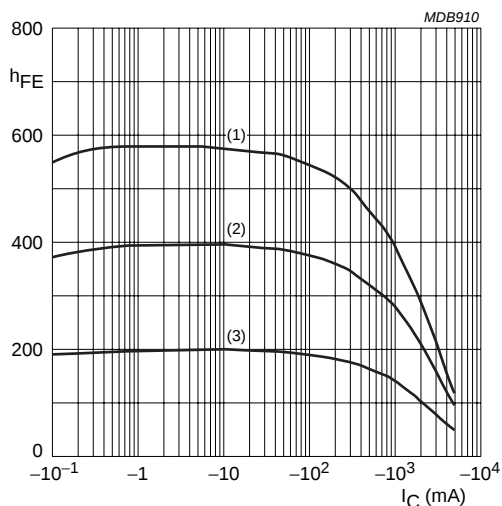
$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector-base cut-off current	$V_{CB} = -30\text{ V}; I_E = 0\text{ A}$	–	–	–100	nA
		$V_{CB} = -30\text{ V}; I_E = 0\text{ A}; T_J = 150\text{ }^{\circ}\text{C}$	–	–	–50	μA
I_{CES}	collector-emitter cut-off current	$V_{CE} = -30\text{ V}; V_{BE} = 0\text{ V}$	–	–	–100	nA
I_{EBO}	emitter-base cut-off current	$V_{EB} = -5\text{ V}; I_C = 0\text{ A}$	–	–	–100	nA
h_{FE}	DC current gain	$V_{CE} = -2\text{ V}$				
		$I_C = -0.1\text{ A}$	200	–	–	
		$I_C = -0.5\text{ A}$	200	–	–	
		$I_C = -1\text{ A}; \text{note 1}$	175	–	450	
		$I_C = -2\text{ A}; \text{note 1}$	140	–	–	
		$I_C = -3\text{ A}; \text{note 1}$	100	–	–	
V_{CEsat}	collector-emitter saturation voltage	$I_C = -0.5\text{ A}; I_B = -50\text{ mA}$	–	–	–70	mV
		$I_C = -1\text{ A}; I_B = -50\text{ mA}$	–	–	–130	mV
		$I_C = -2\text{ A}; I_B = -100\text{ mA}$	–	–	–240	mV
		$I_C = -3\text{ A}; I_B = -300\text{ mA}; \text{note 1}$	–	–	–320	mV
R_{CEsat}	equivalent on-resistance	$I_C = -3\text{ A}; I_B = -300\text{ mA}; \text{note 1}$	–	–	107	$\text{m}\Omega$
V_{BEsat}	base-emitter saturation voltage	$I_C = -2\text{ A}; I_B = -100\text{ mA}$	–	–	–1.1	V
		$I_C = -3\text{ A}; I_B = -300\text{ mA}; \text{note 1}$	–	–	–1.2	V
V_{BEon}	base-emitter turn-on voltage	$V_{CE} = -2\text{ V}; I_C = -1\text{ A}$	–	–	–1.1	V
f_T	transition frequency	$I_C = -100\text{ mA}; V_{CE} = -5\text{ V}; f = 100\text{ MHz}$	100	–	–	MHz
C_c	collector capacitance	$V_{CB} = -10\text{ V}; I_E = I_E = 0\text{ A}; f = 1\text{ MHz}$	–	–	45	pF

Note

1. Pulse test: $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$.

Electrical Characteristic Curve



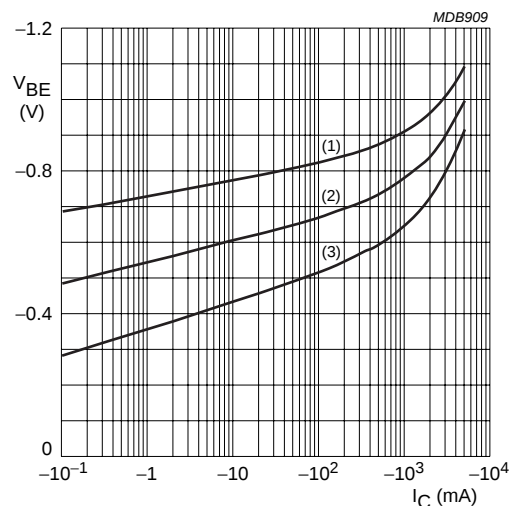
$V_{CE} = -2\text{ V}$.

(1) $T_{amb} = 100^\circ\text{C}$.

(2) $T_{amb} = 25^\circ\text{C}$.

(3) $T_{amb} = -55^\circ\text{C}$.

Fig.1 DC current gain as a function of collector current; typical values.



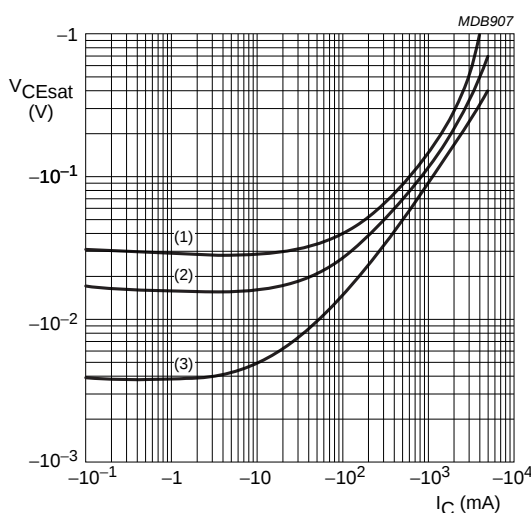
$V_{CE} = -2\text{ V}$.

(1) $T_{amb} = -55^\circ\text{C}$.

(2) $T_{amb} = 25^\circ\text{C}$.

(3) $T_{amb} = 100^\circ\text{C}$.

Fig.2 Base-emitter voltage as a function of collector current; typical values.



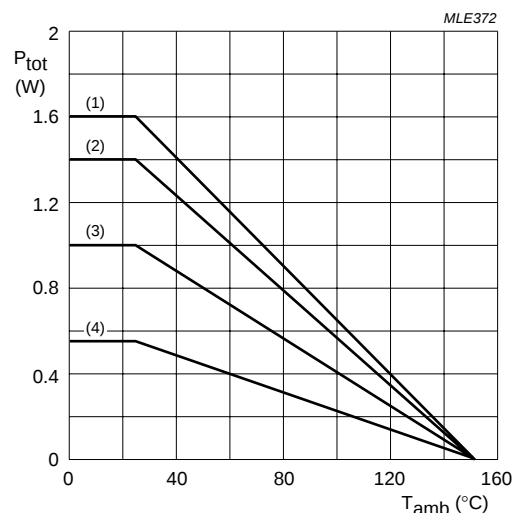
$T_{amb} = 25^\circ\text{C}$.

(1) $I_C/I_B = 100$.

(2) $I_C/I_B = 50$.

(3) $I_C/I_B = 10$.

Fig.3 Collector-emitter saturation voltage as a function of collector current; typical values.



(1) Ceramic PCB; 7 cm² mounting pad for collector.

(2) FR4 PCB; 6 cm² copper mounting pad for collector.

(3) FR4 PCB; 1 cm² copper mounting pad for collector.

(4) Standard footprint.

Fig.4 Power derating curves.